

Date: 4/22/2021

Material Number: SI7217-B-01-IVR

Pkg Config.: PK1409

**Detailed Device Composition** 

No.	Homogeneous Material	Material Weight (mg)	Material Content	CAS Number	Material Weight (%)	Material Weight (mg)	ppm of Material	Wt % of Total Unit	ppm of Total Unit
1	Bond Wire	0.18	Gold	7440-57-5	99.000	0.178	990000	1.1659	11659
			Palladium	7440-05-3	1.000	0.002	10000	0.0118	118
2	Die Attach Epoxy	0.04	Amine	Proprietary	5.000	0.002	50000	0.0128	128
			Epoxy Resin (Proprietary)	Proprietary	20.000	0.008	200000	0.0510	510
			Silver	7440-22-4	75.000	0.029	750000	0.1914	1914
3	Leadframe	5.18	Copper	7440-50-8	94.864	4.914	948640	32.1510	321510
			Magnesium	7439-95-4	0.175	0.009	1750	0.0593	593
			Nickel	7440-02-0	3.200	0.166	32000	1.0845	10845
			Silicon	7440-21-3	0.725	0.038	7250	0.2457	2457
			Silver	7440-22-4	1.036	0.054	10360	0.3511	3511
4	Plating - Internal	0.22	Silver	7440-22-4	100.000	0.220	1000000	1.4394	14394
5	Plating - External	0.67	Tin	7440-31-5	100.000	0.670	1000000	4.3837	43837
6	Mold Compound	8.32	Carbon Black	1333-86-4	0.300	0.025	3000	0.1633	1633
			Epoxy Resin (Proprietary)	Proprietary	7.000	0.582	70000	3.8105	38105
			Phenol Resin (Proprietary)	Proprietary	4.700	0.391	47000	2.5585	25585
			Silicon Dioxide	60676-86-0	88.000	7.322	880000	47.9037	479037
7	Die	0.68	Others	Proprietary	5.000	0.034	50000	0.2208	2208
			Silicon	7440-21-3	95.000	0.641	950000	4.1956	41956
	Total Unit Weight =	15.29				15.29		100.0000	1000000